

Dual surface mount switching diode

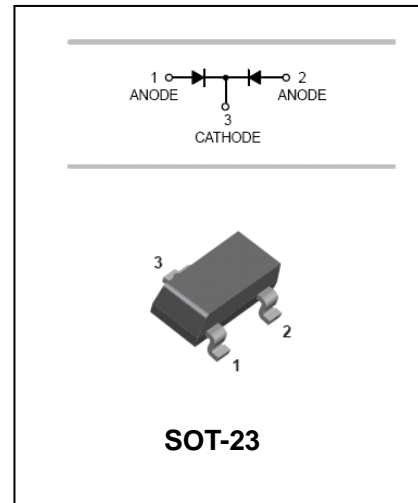
DAN202

FEATURES

- High speed.
- High reliability.
- Suitable for high packing density layout.



Lead-free



APPLICATIONS

- Ultra high speed switching.
- Silicon epitaxial planar.

ORDERING INFORMATION

Type No.	Marking	Package Code
DAN202	N	SOT-23

MAXIMUM RATING @ Ta=25°C unless otherwise specified

Parameter	Symbol	Limits	Unit
Non-Repetitive Peak reverse voltage	V_{RM}	80	V
DC Reverse Voltage	V_R	80	V
Forward continuous Current(Single)	I_{FM}	300	mA
Forward continuous Current(Double)	I_{FM}	450	mA
Average rectified forward current(Single)	I_O	100	mA
Average rectified forward current(Double)	I_O	150	mA
Non-repetitive forward Surge Current @t=1.0us(Single) @t=1.0us(Double)	I_{surge}	4 6	A
Power Dissipation	P_d	200	mW
Thermal resistance, junction to ambient air	$R_{\theta JA}$	357	°C/W
Junction temperature	T_j	150	°C
Storage temperature range	T_{stg}	-55 to +150	°C

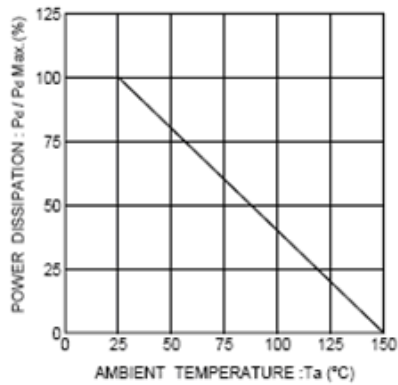
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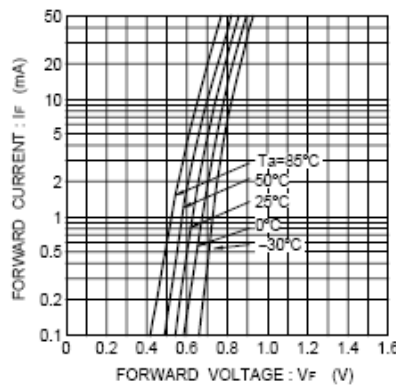
ELECTRICAL CHARACTERISTICS @ Ta=25°C unless otherwise specified

Parameter	Symbol	Test conditions	MIN	MAX	UNIT
Reverse voltage leakage current	I_R	$V_R=70V$		0.1	μA
Forward voltage	V_F	$I_F=100mA$		1.2	V
Total capacitance	C_T	$V_R=6V, f=1MHz$		3.5	pF
Reverse recovery time	t_{rr}	$I_F=5mA, V_R=6V, R_L=50\Omega$		4	ns

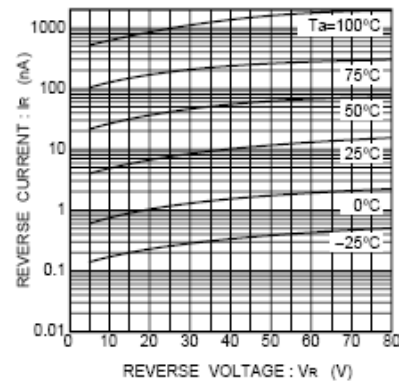
TYPICAL CHARACTERISTICS @ Ta=25°C unless otherwise specified



Power attenuation curve



Forward characteristics



Reverse characteristics

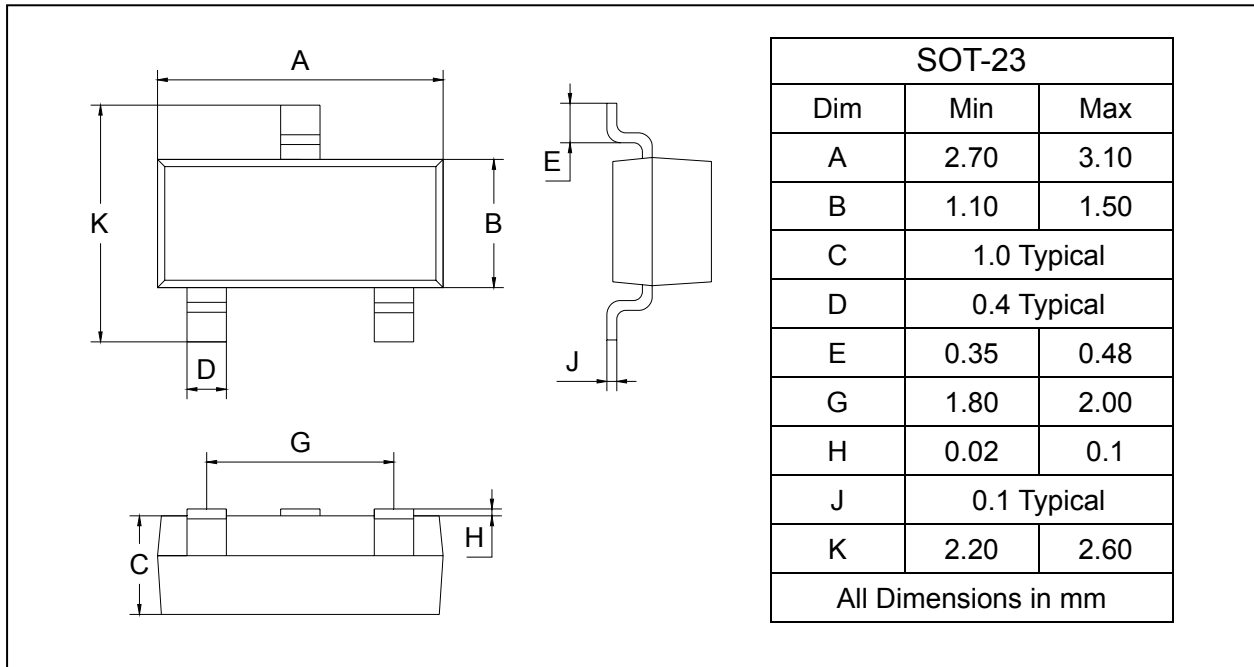
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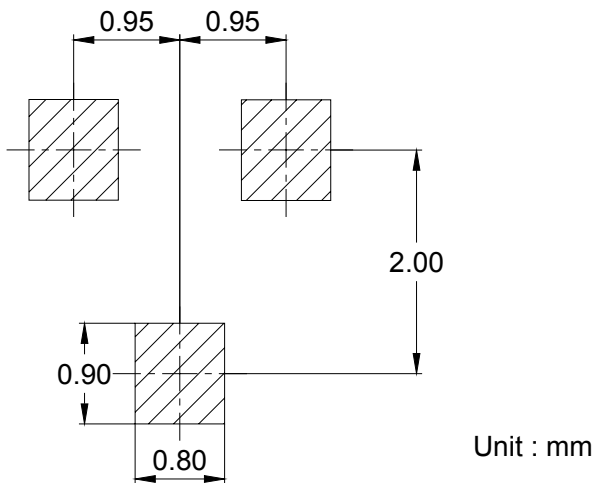
PACKAGE OUTLINE

Plastic surface mounted package

SOT-23



SOLDERING FOOTPRINT



PACKAGE INFORMATION

Device	Package	Shipping
DAN202	SOT-23	3000/Tape&Reel

www.s-manuals.com